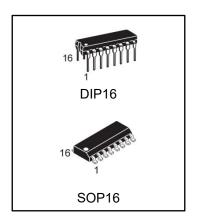


# **High Voltage, High Current Darlington Transistor Arrays**

### **General Description**

The seven NPN Darlington connected transistors in these arrays are well suited for driving lamps, relays, or printer hammers in a variety of industrial and consumer applications. Their high breakdown voltage and internal suppression diodes insure freedom from problems associated with inductive loads. Peak inrush currents to 500 mApermit them to drive incandescent lamps.

The MC1413, B with a 2.7 k $\Omega$  series input resistor is well suited for systems utilizing a 5.0 V TTL or CMOS Logic.

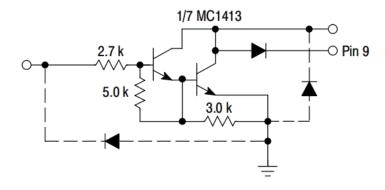


### **Ordering Information**

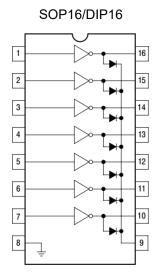
DEVICE	Package Type	MARKING	Packing	Packing Qty
MC1413N	DIP16	MC1413	TUBE	1000pcs/Box
MC1413M/TR	SOP16	MC1413	REEL	2500pcs/Reel
MC1413BN	DIP16	MC1413B	TUBE	1000pcs/Box
MC1413BM/TR	SOP16	MC1413B	REEL	2500pcs/Reel



# **Representative Schematic Diagram**



# **Pin Connections**





#### **Maximum Ratings** (TA = 25°C, and rating apply to any one device in the package, unless otherwise noted.)

Rating	Symbol	Value	Unit
Output Voltage	Vo	50	V
Input Voltage	VI	30	V
Collector Current - Continuous	IC	500	mA
Base Current - Continuous	ΙΒ	25	mA
Operating Ambient Temperature Range MC1413 MC1413B	ТА	-20 to +85 -40 to +85	${\mathbb C}$
Storage Temperature Range	T <sub>stg</sub>	−55 to +150	$^{\circ}$
Junction Temperature	TJ	150	$^{\circ}$
Thermal Resistance, Junction-to-Ambient: N Suffix M Suffix	R <sub>0</sub> JA	67 100	°C/W
Thermal Resistance, Junction-to-Case: N Suffix M Suffix	Rejc	22 20	°C/W
Electrostatic Discharge Sensitivity (ESD)Human Body Model (HBM)  Machine Model (MM) Charged Device Model (CDM)	ESD	2000 400 1500	٧

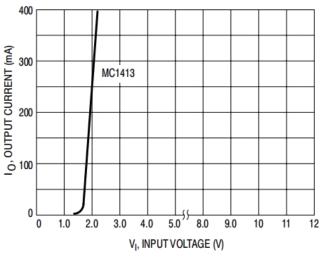
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **Electrical Characteristics** (TA = 25°C, unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit	
Output Leakage Current							
(VO = 50 V, TA = +85°C)		ICEX	-	-	100	μA	
(VO = 50 V, TA = +25°C)			-	-	50		
Collector-Emitter Saturation Voltage							
(IC = 350 mA, IB = 500 μA)	V05( 1)	_	1.1 1.6	,			
(IC = 200 mA, IB = 350 μA)		VCE(sat)	_	0.95	1.3	V	
(IC = 100 mA, IB = 250 μA)			ı	0.85	1.1		
Input Current - On Condition(VI = 3.85 V)		II(on)	ı	0.93	1.35	mA	
Input Voltage - On Condition							
(VCE = 2.0 V, IC = 200 mA)	VI(on)	-	-	2.4	V		
(VCE = 2.0 V, IC = 250 mA)		-	-	2.7			
(VCE = 2.0 V, IC = 300 mA)		_	_	3.0			
Input Current – Off Condition(IC = 500 μA, TA = 85°	℃)	II(off)	50	100	-	μΑ	
DC Current Gain	hFE	1000	-	-	-		
(VCE = 2.0 V, IC = 350 mA)							
Input Capacitance		CI	ı	15	30	pF	
Turn-On Delay Time (50% E <sub>I</sub> to 50% EO)	ton	1	0.25	1.0	μs		
Turn-Off Delay Time (50% E <sub>I</sub> to 50% E <sub>O</sub> )	toff	ı	0.25	1.0	μs		
Clamp Diode Leakage Current	TA = +25°C		_	_	50		
(VR = 50 V)	TA = +85°C	lR	-	-	100	μA	
Clamp Diode Forward Voltage(IF = 350 mA)		VF	-	1.5	2.0	V	



### Typical Performance Curves TA = 25°C



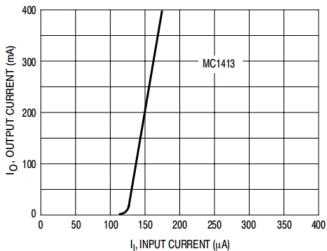
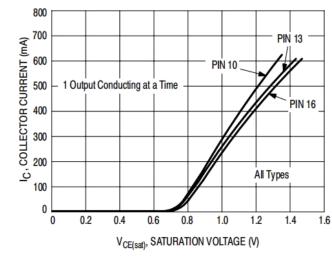


Figure 3. Output Current versus Input Voltage





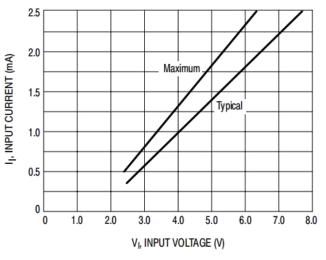


Figure 5. Typical Output Characteristics

Figure 6. Input Characteristics

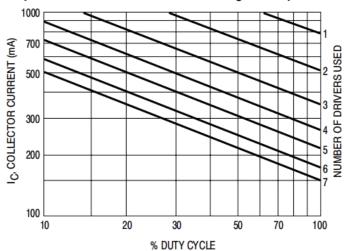
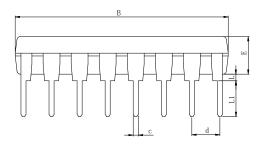


Figure 7. Maximum Collector Current versus Duty Cycle (and Number of Drivers in Use)

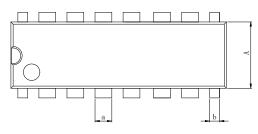


# **Physical Dimensions**

DIP16

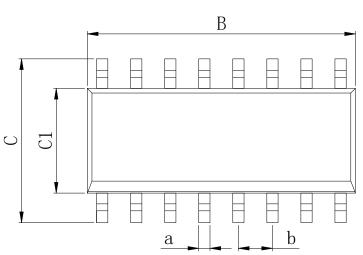


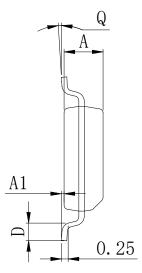




Dimensions In Millimeters(DIP16)											
Symbol:	Α	В	D	D1	E	L	L1	а	b	С	d
Min:	6.10	18.94	8.40	7.42	3.10	0.50	300	1.50	0.85	0.40	2.54 BSC
Max:	6.68	19.56	9.00	7.82	3.55	0.70	3.60	1.55	0.90	0.50	2.54 BSC

SOP16





Dimensions In Millimeters(SOP16)									
Symbol:	А	A1	В	С	C1	D	Q	а	b
Min:	1.35	0.05	9.80	5.80	3.80	0.40	0°	0.35	1 27 DCC
Max:	1.55	0.20	10.0	6.20	4.00	0.80	8°	0.45	1.27 BSC



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NLV37WZ17USG 74HCT126T14-13 74VHC9126FT(BJ) RHRXH162244K1 74AUP1G34FW5-7 74AUP1G07FW5-7 74LVC1G126FW4-7

74LVC2G126RA3-7 74LVCE1G125FZ4-7 54FCT240TLB NLX3G16DMUTCG NLX2G06AMUTCG LE87100NQCT LE87285NQC

LE87290YQC LE87290YQCT 74AUP1G125FW5-7 NLU2G16CMUTCG MC74LCX244MN2TWG NL17SG17P5T5G

NLV74HC125ADR2G NLVHCT245ADTR2G NLVVHC1G126DFT2G EL5623IRZ ISL15102AIRZ-T13 ISL1539IRZ-T13

MC100EP17MNG MC74HCT365ADR2G MC74LCX244ADTR2G NL27WZ126US NL37WZ16US NLU1G07MUTCG NLU2G07MUTCG NLX3G17BMX1TCG